

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5525329

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YEN-CHEN CHEN	12/06/2017
XIAO WU	12/06/2017
HAI TAO LIU	12/06/2017
MING HUA DU	12/06/2017
SHOUGUO ZHANG	12/06/2017
YAO-HUNG LIU	12/06/2017
CHIN-FU LIN	06/26/2017
CHUN-YUAN WU	06/26/2017
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
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City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16413425
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	JCLA70045-D
NAME OF SUBMITTER:	JIawei HUANG
SIGNATURE:	/JIawei HUANG/
DATE SIGNED:	05/15/2019

Total Attachments: 10

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**SEMICONDUCTOR DEVICE AND METOD FOR FABRICATING THE
SAME**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number _____
Filed on _____.

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yen-Chen Chen Date: 12/6/2017

Legal Name of Sole or First Inventor: Yen-Chen Chen

Residence: Tainan City, Taiwan

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(R.O.C.)

UMCD-2017-0133
70045-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Xiao Wu Date: 12/6/2017

Legal Name of Additional Joint Inventor, if any: Xiao Wu

Residence: Singapore, Singapore

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70045-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Hai Tao Liu Date: 12/6/2017

Legal Name of Additional Joint Inventor, if any: Hai Tao Liu

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Ming Hua Du Date: 12/6/2017

Legal Name of Additional Joint Inventor, if any: Ming Hua Du

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Shouguo Zhang Date: 12/6/2017

Legal Name of Additional Joint Inventor, if any: Shouguo Zhang

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UMCD-2017-0133
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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yao-Hung Liu Date: 12/6/2017

Legal Name of Additional Joint Inventor, if any: Yao-Hung Liu

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UMCD-2017-0133
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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Chin-Fu Lin Date: JUN 26 2017

Legal Name of Additional Joint Inventor, if any: Chin-Fu Lin

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Chun-Yuan Wu Date: JUN 26 2017

Legal Name of Additional Joint Inventor, if any: Chun-Yuan Wu

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